

Ultra V

Ultra Discovery™ V



Ultra Discovery™ V AOI System

Orbotech's Ultra Discovery™ V AOI systems offer a new level of AOI performance. Discovery's field-proven SIP Technology™ has been designed to overcome the complex challenges of the most advanced BGA/CSP and COFs.

Simple, Intelligent, Powerful

Ultra Discovery V delivers Simple, Intelligent and Powerful (SIP) AOI performance with 15µm line/space inspection capabilities for BGA, CSP and COF production.

Delivering very clear images essential for capturing the finest defects, the system achieves outstanding AOI results with minimal effort or training, even on complicated panels. Most of manufacturers' valuable time on the system is spent inspecting panels. Logic false calls are virtually eliminated and overall false calls are minimized saving precious verification time.

Benefits

- High throughput and superior detection with minimal number of false calls
- Especially designed for inspection of the finest lines down to 15µm
- Quick setup even for the most complicated jobs for higher productivity
- Automation-ready
- Very high uptime





Push-to-Scan®:

- A 'no set-up' process
- Top AOI results with minimal effort or training
- The easiest, user-friendly interface (GUI)
- Full 'Step and Repeat' functions

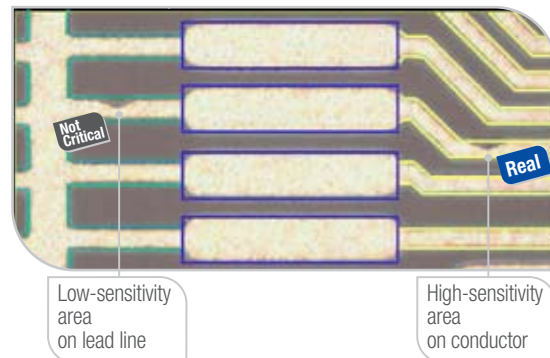
Visual Intelligence:

Using SIP Technology, Ultra Discovery V introduces Orbotech's detection paradigm to the world of fine-line BGA/CSP and COFs production. With the Visual Intelligence Detection Engine – now dedicated for IC substrate applications - manufacturers no longer have to choose between detection and false calls or waste time on non-critical defects. For the first time in AOI, detect all you want, and only what you want.

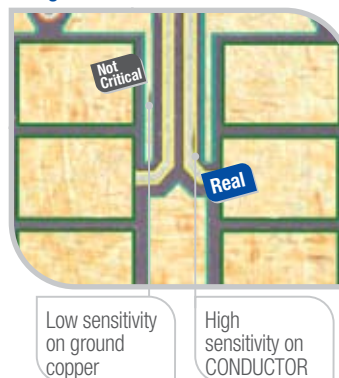
Ultra Discovery V is equipped with a super-fast optical head, which together with its dedicated IC substrate panel understanding, delivers exceptionally high throughput, superior detection and low false call rates. The optical head is specially designed for inspection of the finest lines down to 15µm. The customized professional lens, featuring unique wide angle illumination, delivers super clear images essential for capturing the finest defects.

- Full panel understanding, context-based detection engine
- Equipped with ultra-fast sensors and powerful data processing for maximum inspection speed
- Industry first: low false calls reporting for BGA/CSP and Chip-on-Flex application boards

Different sensitivities for conductors and lead lines



Different sensitivities for conductors and ground area



Different sensitivities for wire bonding pads

